

Filename: PMP8637RevA - LM26001 - 3V3 at 500mA - BoM.xls

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**3.5 .. 35V -> 3.3V @ 500mA**

Quantity	Designator	Value	Description	Package	PartNumber	Manufacturer
1	C1	3.3uF	CAP, CERM, 3.3uF, 50V, +/-10%, X7R, 1210	1210	GRM32DR71H335KA88L	MuRata
1	C2	47uF	CAP, AL, 47uF, 50V, +/-20%, 0.3 ohm, SMD	SMT Radial G	EEE-FC1H470P	Panasonic
1	C3	10uF	CAP, CERM, 10uF, 10V, +/-20%, X7R, 1206	1206	C3216X7R1A106M	TDK
1	C4	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H104KA93D	MuRata
1	C5	0.01uF	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H103KA01D	MuRata
1	C6	22uF	CAP, CERM, 22uF, 10V, +/-10%, X7R, 1206	1206	GRM31CR71A226KE15L	MuRata
1	C8	0.033uF	CAP, CERM, 0.033uF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H333KA61D	MuRata
1	C9	330pF	CAP, CERM, 330pF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H331KA01D	MuRata
1	D1	60V	Diode, Schottky, 60V, 1A, SMA	SMA	SS16T3G	ON Semiconductor
7	EN, GND-IN, GND-OUT, PGOOD, SYNC, VIN, VOUT	None	Test point, 55 mil SMT	None	None	None
2	J-FPWM, J- VBIAS		Header, TH, 100mil, 3x1, Gold plated, 230 mil above insulator	3x1 Header	TSW-103-07-G-S	Samtec, Inc.
1	L1	47uH	Inductor, Shielded Drum Core, Ferrite, 47uH, 1.15A, 0.25 ohm, SMD	LPS6235	LPS6235-473MLB	Coilcraft
1	R1	16.9k	RES, 16.9k ohm, 1%, 0.1W, 0603	0603	CRCW060316K9FKEA	Vishay-Dale
2	R2, R6	10.0k	RES, 10.0k ohm, 1%, 0.1W, 0603	0603	CRCW060310K0FKEA	Vishay-Dale
1	R3	93.1k	RES, 93.1k ohm, 1%, 0.1W, 0603	0603	CRCW060393K1FKEA	Vishay-Dale
1	R4	100k	RES, 100k ohm, 1%, 0.1W, 0603	0603	CRCW0603100KFKEA	Vishay-Dale
1	R5	1.82k	RES, 1.82k ohm, 1%, 0.1W, 0603	0603	CRCW06031K82FKEA	Vishay-Dale
1	R101	49.9	RES, 49.9 ohm, 1%, 0.1W, 0603	0603	CRCW060349R9FKEA	Vishay-Dale
1	U1	LM26001-Q1	1.5A Switching Regulator with High Efficiency Sleep Mode	MXA16A	LM26001-Q1	Texas Instruments

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